



Third International Symposium on Tin Whiskers

June 23, 2009

8:30	Welcome	Dr. Michael Osterman	CALCE
8:45	Denmark Technical University	Dr. Rajan Ambat	DTU
9:00	Whisker Research Efforts and Findings by JEITA	Prof. Katsuaki Suganuma	Osaka
9:30	Whiskers: An ESA Perspective	Barrie Dunn	ESA
10:00	Break		
10:15	Evaluation of Tin Whisker Growth in Vacuumed Thermal Cycling Conditions	Norio Nemoto	JAXA
10:45	Effect of Grain Size on Pressure-Induced Tin Whisker Formation	Dr. Tadahiro Shibutani	Yokohama National University
11:15	The Influence of the Flux Content and Circumstances on Whisker Growth at the Solder Fillet	Minoru Ueshima	Senju Metals
11:45	Lunch		
1:00	Tin Whisker and Surface Defect Formation on Electroplated Films and Reflowed Joints	Prof. Carol Handwerker	Purdue University
1:30	Driving Force for Whisker Formation on Sn Thin Films	Matthias Sobiech	Max Planck Institute for Metals Research
2:00	Superior, Whisker-Reduced Immersion Tin Technology with Organic Nanometal	Nils Arendt	Ormecon/Enthone
2:30	Break		
2:45	Simultaneous and Time-Resolved Measurement of Stress in Sn and Sn-Cu Electrodeposits Using Cantilever Beams and X-ray Diffraction	Dr. Maureen Williams	NIST
3:15	Zinc Whiskers from Electrodeposited Films	Dr Geoffrey D. Wilcox	Loughborough University
3:45	The Relationship between Composition and Tin Whisker Formation in Sn-Cu-Pb Electroplated Tin Films	Pylin Sarobol	Purdue University
4:15	Adjourn		

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8:30	Tin Whisker Test Methods and Findings	Dr. Michael Osterman	CALCE
9:00	Measuring the Mitigation Capability of Conformal Coatings	Dr. Chris Hunt	NPL
9:30	Evaluation of Conformal Coating for Mitigation of Tin Whisker Growth	Tsuyoshi Nakagawa	Nippon Avionics Co.
10:00	Tin Whisker Containment and Environmental Protection with Flexible Ceramic Conformal Coatings	Ofer-Sundew	Sundew
10:30	Break		
11:00	Tin Whisker Mitigation using Robotic Hot Solder Dip	Joseph Zaccari	Corfin
11:30	Effectiveness of Solder Dipping in Mitigating Tin Whiskers	Dr. Diganta Das	CALCE
12:00	Lunch		
1:00	Developing an Empirical Model for Estimating the Probability of Electrical Short Circuits from Tin Whiskers – Part II	D. Karim Courey	NASA
1:30	Electrical Shorting Potential of Tin Whiskers	Dr. Michael Osterman	CALCE
2:00	Adjourn		

Registration and hotel information can be found at
<http://www.smta.org/education/symposia/symposia.cfm#tin-whiskers>

